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INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Application Number	UNKNOWN 10/666,432
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				First Named Inventor	Vishwas V. Hardikar
				Group Art Unit	UNKNOWN 1742
				Examiner Name	UNKNOWN Leader
Sheet	1	of	1	Attorney Docket Number	004.0108

OTHER ART

(Including Author, Title, Date, Pertinent Pages, Etc.)

WL		"Electrodeposition of Copper Thin Film on Ruthenium - A Potential Diffusion Barrier for Cu Interconnects", Oliver Chyan et al., Journal of The Electrochemical Society, Volume 150, Number 5 (2003)
WL		"Seedless Superfill: Copper Electrodeposition in Trenches with Ruthenium Barriers", D. Josell et al., Electrochemical and Solid State Letters, June 5, 2003
WL		"Liner Materials for Direct Electrodeposition of Cu", M.W.Lane et al., Applied Physics Letter, Volume 83, Number 12, September 22, 2003
WL		"International Technology Roadmap for Semiconductors", 2001

William Leader 4/18/2007